

HVB187YP

Silicon Epitaxial Planar Pin Diode for High Frequency Attenuator

REJ03G0439-0100

(Previous: ADE-208-1411)

Rev.1.00 Dec 16, 2004

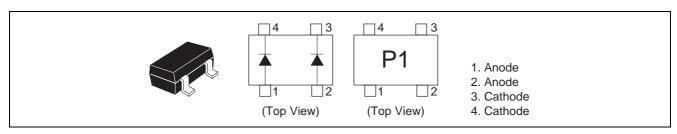
Features

- Low forward resistance. (rf = 5.5Ω max)
- CMPAK-4 package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HVB187YP	P1	CMPAK-4

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V _R	60	V
Forward current	l _F	50	mA
Power dissipation	Pd *1	100	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

Note: 1. Per one device.

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _R	_	_	100	nA	V _R = 60 V
Forward voltage	V _F	_	_	1.0	V	I _F = 10 mA
Capacitance	С	_	_	2.4	pF	V _R = 0 V, f = 1 MHz
Forward resistance	r _f	3. 5	_	5.5	Ω	I _F = 10 mA, f = 100 MHz
ESD-Capability *1	_	200	_	_	V	$C = 200 \text{ pF}, R = 0 \Omega, Both forward}$
						and reverse direction 1 pulse.

Note: 1. Failure criterion; $I_R > 100$ nA at $V_R = 60$ V

Main Characteristic

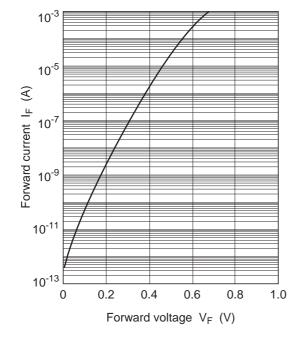


Fig.1 Forward current vs. Forward voltage

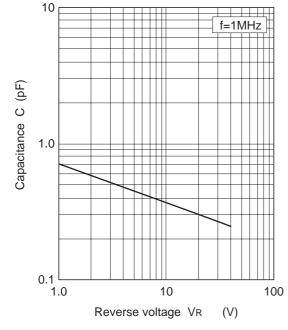


Fig.3 Capacitance vs. Reverse voltage

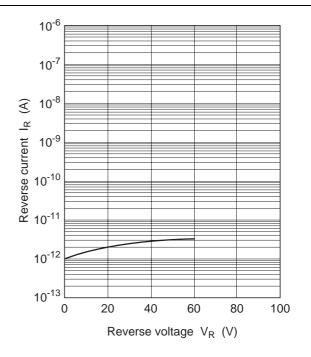


Fig.2 Reverse current vs. Reverse voltage

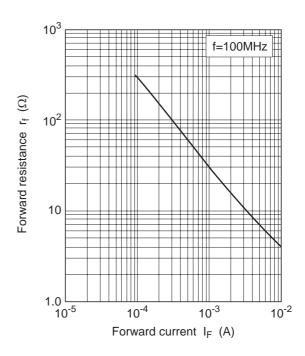
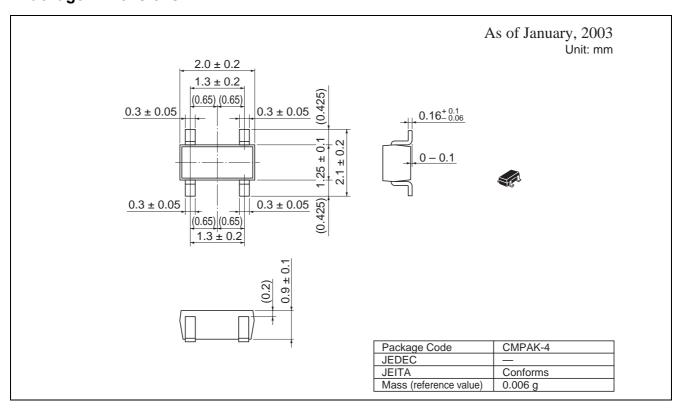


Fig.4 Forward resistance vs. Forward current

Package Dimensions



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